

## APPENDIX

## Changes to Claims:

The following are marked-up versions of the amended claims:

7. (Amended) The semiconductor device as defined in claim 1any one of claims 1 to 6,

wherein a recognition hole is formed in the substrate at a position differing from the holes; and

wherein a recognition pattern is formed over the recognition hole on the side of a surface of the substrate including the interconnecting pattern.

10. (Amended) The semiconductor device as defined in claim 1any one of claims 1 to 6,

wherein the conductive members are a plurality of layered bumps.

17. (Amended) The semiconductor device as defined in claim 1any one of claims 1 to 6,

wherein the semiconductor chip is mounted face-down to the substrate.

18. (Amended) A circuit board over which is mounted the semiconductor device as defined in claim 1any one of claims 1 to 6.

19. (Amended) An electronic instrument provided with the semiconductor device as defined in claim 1any one of claims 1 to 6.

27. (Amended) The method of fabricating a semiconductor device as defined in claim 20any one of claims 20 to 26, further comprising

a step of forming a recognition hole in the substrate at a position differing from the holes, and forming a recognition pattern over the recognition hole on the side of a surface of the substrate including the interconnecting pattern.

29. (Amended) The method of fabricating a semiconductor device as defined in claim 20~~any one of claims 20 to 26~~,  
wherein the conductive members are a plurality of layered bumps

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